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REVISION HISTORY

Revision PrA 15-Nov-04: Preliminary Version

FUNCTIONAL BLOCK DIAGRAM

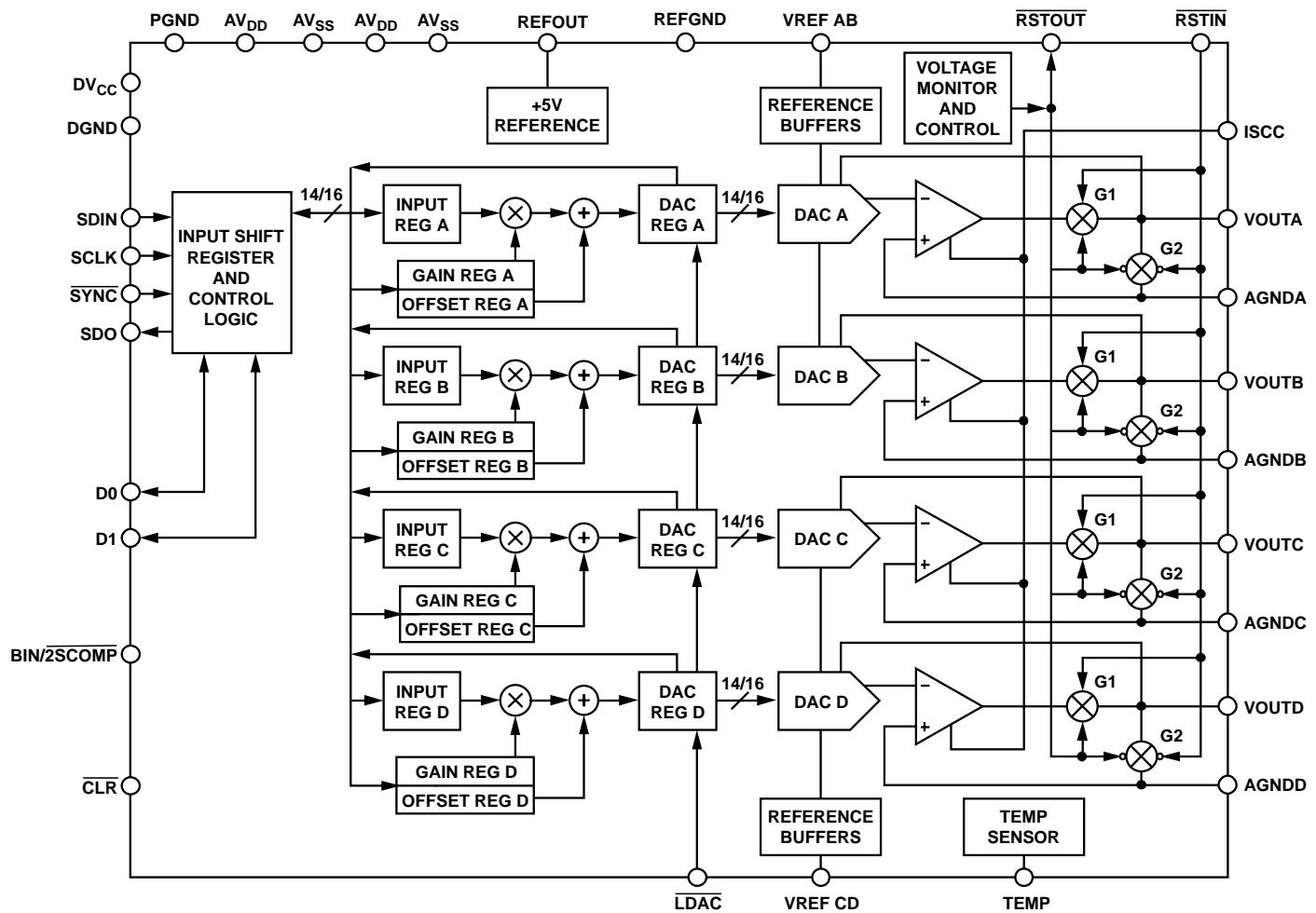


Figure 1. Functional Block Diagram

SPECIFICATIONS

$AV_{DD} = +11.4$ V to $+16.5$ V, $AV_{SS} = -11.4$ V to -16.5 V, $AGND = DGND = REFGND = PGND = 0$ V; $REFAB = REFCD = 5$ V Ext; $DV_{CC} = 2.7$ V to 5.5 V, $R_{LOAD} = 10$ k Ω , $C_L = 200$ pF. All specifications T_{MIN} to T_{MAX} , unless otherwise noted.

Table 1.

Parameter	A Grade ¹	B Grade ¹	C Grade ¹	Unit	Test Conditions/Comments
ACCURACY					
Resolution	16 14	16 14	16 14	Bits	AD5764 AD5744
Relative Accuracy (INL)	± 4	± 2	± 1	LSB max	
Differential Nonlinearity	± 1	± 1	± 1	LSB max	Guaranteed monotonic
Bipolar Zero Error	± 1	± 1	± 1	mV max	At 25°C. Error at other temperatures obtained using bipolar zero TC.
Bipolar Zero TC	± 2	± 2	± 2	ppm FSR/°C max	
Zero Code Error	± 1	± 1	± 1	mV max	At 25°C. Error at other temperatures obtained using zero code TC.
Zero Code TC	± 2	± 2	± 2	ppm FSR/°C max	
Gain Error	± 0.02	± 0.02	± 0.02	% FSR max	At 25°C. Error at other temperatures obtained using gain TC.
Gain TC	2	2	2	ppm FSR/°C max	
DC Crosstalk ²	0.5	0.5	0.5	LSB max	
REFERENCE INPUT/OUTPUT					
Reference Input ²					
Reference Input Voltage	5	5	5	V nom	$\pm 1\%$ for specified performance
DC Input Impedance	1	1	1	M Ω min	Typically 100 M Ω
Input Current	± 10	± 10	± 10	μ A max	Typically ± 30 nA
Reference Range	1/5	1/5	1/5	V min/max	
Reference Output					
Output Voltage	4.999/5.001	4.999/5.001	4.999/5.001	V min/max	At 25°C
Reference TC	± 10	± 10	± 10	ppm/°C max	
Output Noise(0.1 Hz to 10 Hz)	TBD	TBD	TBD	μ V p-p typ	
Noise Spectral Density	TBD	TBD	TBD	nV/ $\sqrt{\text{Hz}}$ typ	
OUTPUT CHARACTERISTICS ²					
Output Voltage Range ³	± 10 ± 13	± 10 ± 13	± 10 ± 13	V min/max	$AV_{DD}/AV_{SS} = \pm 11.4$ V $AV_{DD}/AV_{SS} = \pm 16.5$ V
Output Voltage TC	± 2	± 2	± 2	ppm FSR/°C max	
Output Voltage Drift V_s Time	\pm TBD	\pm TBD	\pm TBD	ppm FSR/1000 Hours typ	
Short Circuit Current	10	10	10	mA max	$R_{SCC} = 6$ k Ω , See Figure ???
Load Current	± 1	± 1	± 1	mA max	For specified performance
Capacitive Load Stability					
$R_L = \infty$	200	200	200	pF max	
$R_L = 10$ k Ω	TBD	TBD	TBD	pF max	
DC Output Impedance	0.3	0.3	0.3	Ω max	
DIGITAL INPUTS ²					
V_{IH} , Input High Voltage	2	2	2	V min	$DV_{CC} = 2.7$ V to 5.5 V, JEDEC compliant

¹ Temperature range -40°C to $+85^{\circ}\text{C}$; typical at $+25^{\circ}\text{C}$. Device functionality is guaranteed to $+105^{\circ}\text{C}$ with degraded performance.

² Guaranteed by characterization. Not production tested.

³ Output amplifier headroom requirement is 1.4 V min.

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Parameter	A Grade ¹	B Grade ¹	C Grade ¹	Unit	Test Conditions/Comments
V _{IL} , Input Low Voltage	0.8	0.8	0.8	V max	
Input Current	±10	±10	±10	µA max	
Pin Capacitance	10	10	10	pF max	Total for All Pins. T _A = T _{MIN} to T _{MAX} .
DIGITAL OUTPUTS (D0,D1, SDO) ²					
Output Low Voltage	0.4	0.4	0.4	V max	DV _{CC} = 5 V ± 10%, sinking 200 µA
Output High Voltage	DV _{CC} – 1	DV _{CC} – 1	DV _{CC} – 1	V min	DV _{CC} = 5 V ± 10%, Sourcing 200 µA
Output Low Voltage	0.4	0.4	0.4	V max	DV _{CC} = 2.7 V to 3.6 V, Sinking 200 µA
Output High Voltage	DV _{CC} – 0.5	DV _{CC} – 0.5	DV _{CC} – 0.5	V min	DV _{CC} = 2.7 V to 3.6 V, Sourcing 200 µA
High Impedance Leakage Current	±1	±1	±1	µA max	SDO only
High Impedance Output Capacitance	5	5	5	pF typ	SDO only
TEMP SENSOR					
Accuracy	±1	±1	±1	°C typ	At 25°C
	±5	±5	±5	°C max	–40°C < T < +85°C
Output Voltage @ 25°C	1.5	1.5	1.5	V typ	
Output Voltage Scale Factor	5	5	5	mV/°C typ	
Output Voltage Range	0/3.0	0/3.0	0/3.0	V min/max	
Output Load Current	200	200	200	µA max	Current source only.
Power On Time	10	10	10	ms typ	To within ±5°C
POWER REQUIREMENTS					
A _{VDD} /A _{VSS}	11.4/16.5	11.4/16.5	11.4/16.5	V min/max	
DV _{CC}	2.7/5.5	2.7/5.5	2.7/5.5	V min/max	
Power Supply Sensitivity ⁴					
ΔV _{OUT} /ΔA _{VDD}	–85	–85	–85	dB typ	
A _{I_{DD}}	3.75	3.75	3.75	mA/Channel max	Outputs unloaded
A _{I_{SS}}	2.75	2.75	2.75	mA/Channel max	Outputs unloaded
D _{I_{CC}}	1	1	1	mA max	V _{IH} = DV _{CC} , V _{IL} = DGND, TBD mA typ
Power Dissipation	244	244	244	mW typ	±12 V operation output unloaded

⁴ Guaranteed by characterization. Not production tested.

AC PERFORMANCE CHARACTERISTICS

$AV_{DD} = +11.4$ V to $+16.5$ V, $AV_{SS} = -11.4$ V to -16.5 V, $AGND = DGND = REFGND = PGND = 0$ V; $REFAB = REFCD = 5$ V Ext; $DV_{CC} = 2.7$ V to 5.5 V, $R_{LOAD} = 10$ k Ω , $C_L = 200$ pF. All specifications T_{MIN} to T_{MAX} , unless otherwise noted. Guaranteed by design and characterization, not production tested.

Table 2.

Parameter	A Grade	B Grade	C Grade	Unit	Test Conditions/Comments
DYNAMIC PERFORMANCE					
Output Voltage Settling Time	8 10 1	8 10 1	8 10 1	μ s typ μ s max μ s max	Full-scale step
Slew Rate	5	5	5	V/ μ s typ	512 LSB step settling @ 16 Bits
Digital-to-Analog Glitch Energy	5	5	5	nV-s typ	
Glitch Impulse Peak Amplitude	5	5	5	mV max	
Channel-to-Channel Isolation	100	100	100	dB typ	
DAC-to-DAC Crosstalk	5	5	5	nV-s typ	
Digital Crosstalk		5	5	nV-s typ	
Digital Feedthrough		1	1	nV-s typ	Effect of input bus activity on DAC output under test
Output Noise (0.1 Hz to 10 Hz)	0.1	0.1	0.1	LSB p-p typ	
Output Noise (0.1 kHz to 100 kHz) ⁵	45	45	45	μ V rms max	
1/f Corner Frequency	1	1	1	kHz typ	
Output Noise Spectral Density	60	60	60	nV/ $\sqrt{\text{Hz}}$ typ	Measured at 10 kHz
Complete System Output Noise Spectral Density ⁶	80	80	80	nV/ $\sqrt{\text{Hz}}$ typ	Measured at 10 kHz

⁵ Guaranteed by design and characterization. Not production tested.⁶ Includes noise contributions from integrated reference buffers, 14/16-bit DAC and output amplifier.

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TIMING CHARACTERISTICS

$AV_{DD} = +11.4$ V to $+16.5$ V, $AV_{SS} = -11.4$ V to -16.5 V, $AGND = DGND = REFGND = PGND = 0$ V; $REFAB = REFCD = 5$ V Ext; $DV_{CC} = 2.7$ V to 5.5 V, $R_{LOAD} = 10$ k Ω , $C_L = 200$ pF. All specifications T_{MIN} to T_{MAX} , unless otherwise noted.

Table 3.

Parameter ^{7,8,9}	Limit at T_{MIN}, T_{MAX}	Unit	Description
t_1	33	ns min	SCLK cycle time
t_2	13	ns min	SCLK high time
t_3	13	ns min	SCLK low time
t_4	13	ns min	\overline{SYNC} falling edge to SCLK falling edge setup time
t_5 ¹⁰	13	ns min	24 th SCLK falling edge to \overline{SYNC} rising edge
t_6	40	ns min	Minimum \overline{SYNC} high time
t_7	5	ns min	Data setup time
t_8	0	ns min	Data hold time
t_9	20	ns min	\overline{SYNC} rising edge to \overline{LDAC} falling edge
t_{10}	20	ns min	\overline{LDAC} pulse width low
t_{11}	5	ns min	\overline{LDAC} falling edge to DAC output response time
t_{12}	10	μ s max	DAC output settling time
t_{13}	20	ns min	\overline{CLR} pulse width low
t_{14}	12	μ s max	\overline{CLR} pulse activation time
t_{15} ^{11,12}	20	ns max	SCLK rising edge to SDO valid
t_{16} ¹²	8	ns min	SCLK falling edge to \overline{SYNC} rising edge
t_{17} ¹²	20	ns min	\overline{SYNC} rising edge to \overline{LDAC} falling edge

⁷ Guaranteed by design and characterization. Not production tested.

⁸ All input signals are specified with $t_r = t_f = 5$ ns (10% to 90% of DV_{CC}) and timed from a voltage level of 1.2 V.

⁹ See Figure 2, Figure 3, and Figure 4.

¹⁰ Stand-alone mode only.

¹¹ Measured with the load circuit of Figure 5.

¹² Daisy-chain mode only.

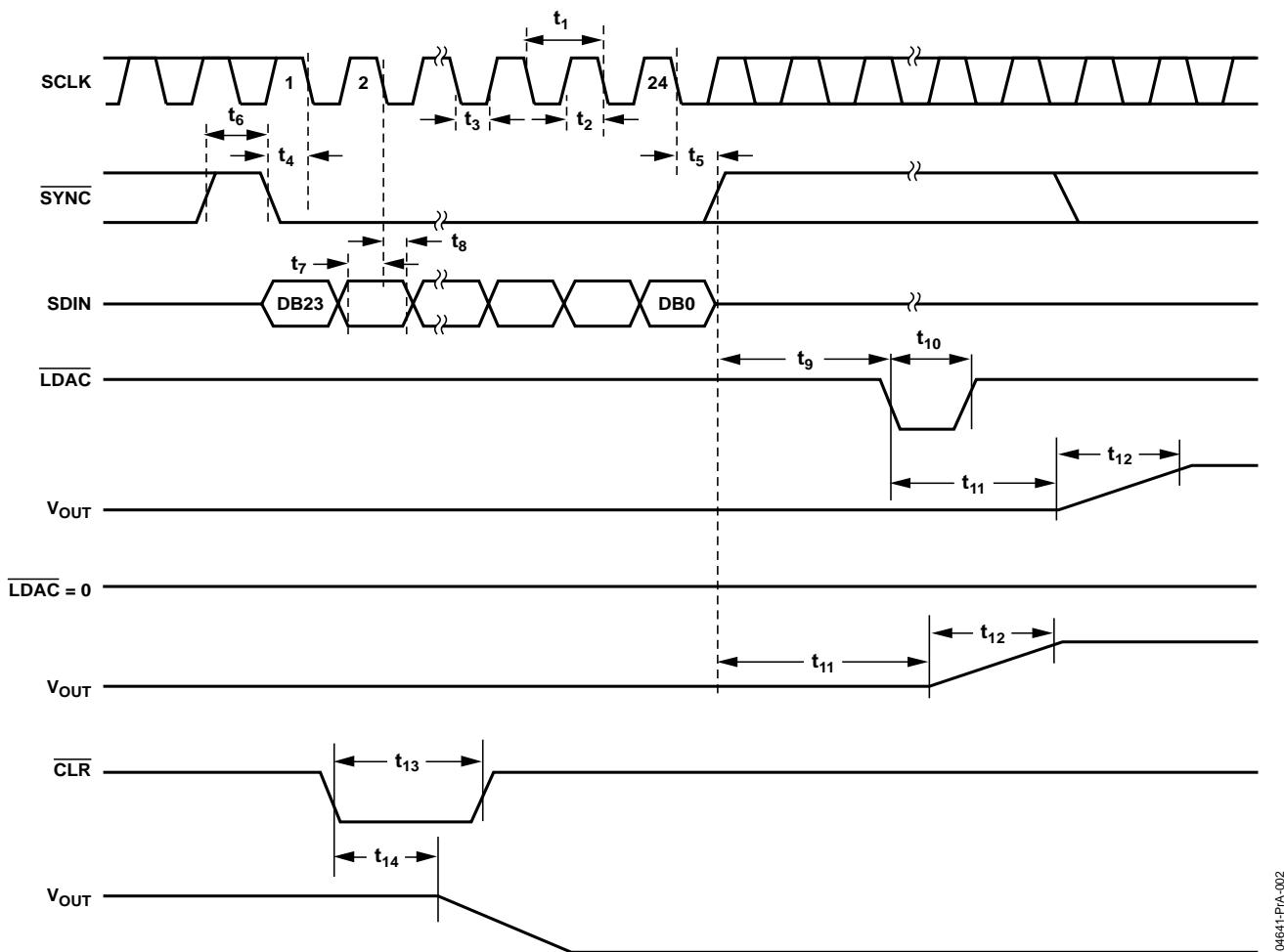


Figure 2. Serial Interface Timing Diagram

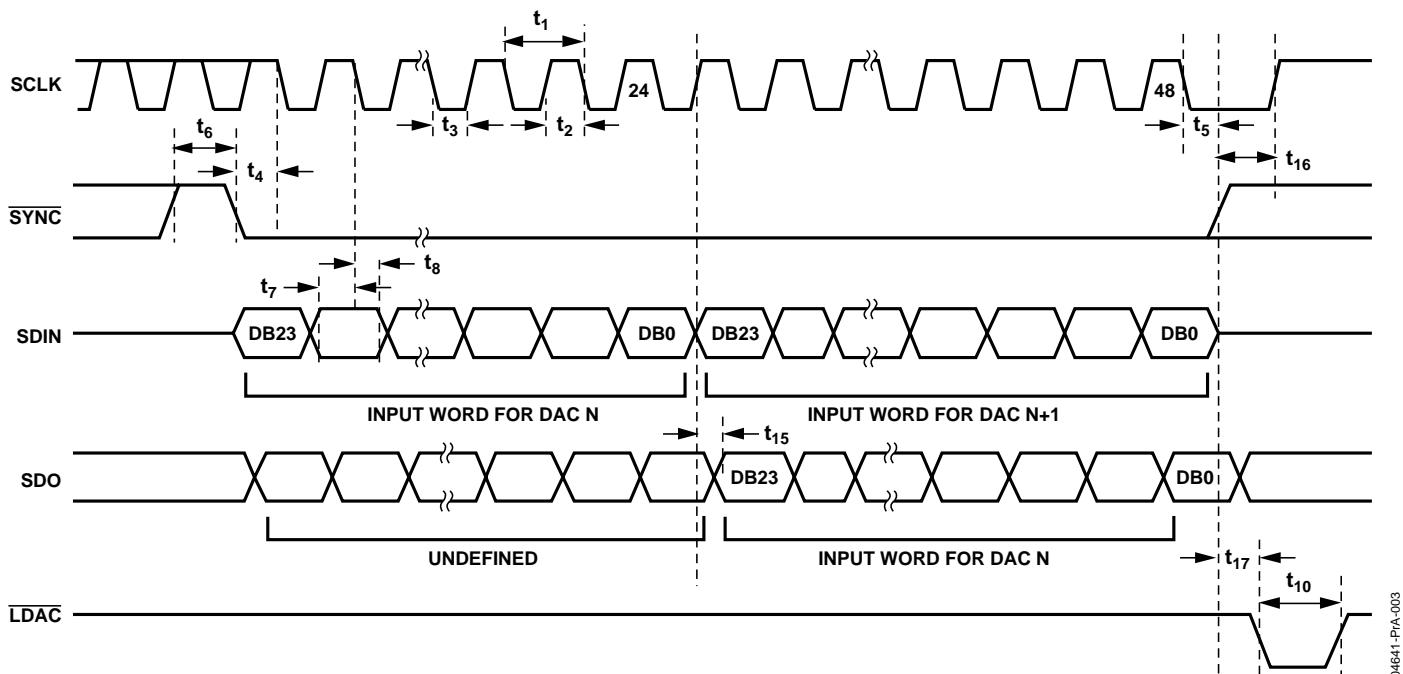


Figure 3. Daisy Chain Timing Diagram

Preliminary Technical Data

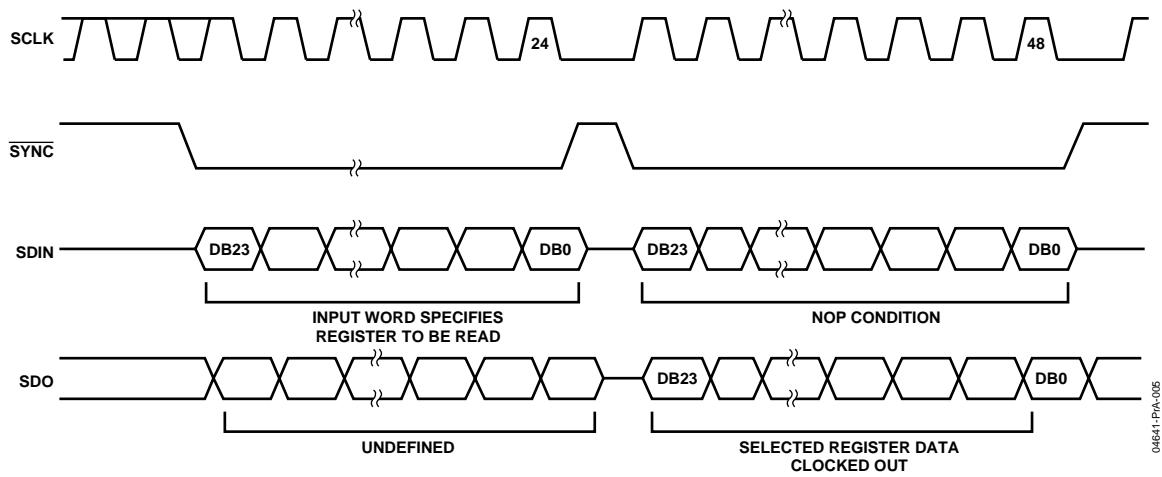


Figure 4. Readback Timing Diagram

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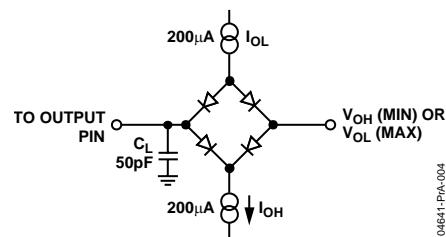


Figure 5. Load Circuit for SDO Timing Diagram

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$ unless otherwise noted.

Transient currents of up to 100 mA will not cause SCR latch-up.

Table 4.

Parameter	Rating
AV_{DD} to AGND, DGND	-0.3 V to +17 V
AV_{SS} to AGND, DGND	+0.3 V to -17 V
DV_{CC} to DGND	-0.3 V to +7 V
Digital Inputs to DGND	-0.3 V to $DV_{CC} + 0.3$ V
Digital Outputs to DGND	-0.3 V to $DV_{CC} + 0.3$ V
REF IN to AGND, PWRGND	-0.3 V to +17 V
REF OUT to AGND	AV_{SS} to AV_{DD}
$V_{OUTA,B,C,D}$ to AGND	AV_{SS} to AV_{DD}
AGND to DGND	-0.3 V to +0.3 V
Operating Temperature Range Industrial	-40°C to +85°C
Storage Temperature Range	-65°C to +150°C
Junction Temperature (T_J max)	150°C
32-Lead TQFP Package, θ_{JA} Thermal Impedance	TBD°C/W
Reflow Soldering	
Peak Temperature	220°C
Time at Peak Temperature	10 sec to 40 sec

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although this product features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

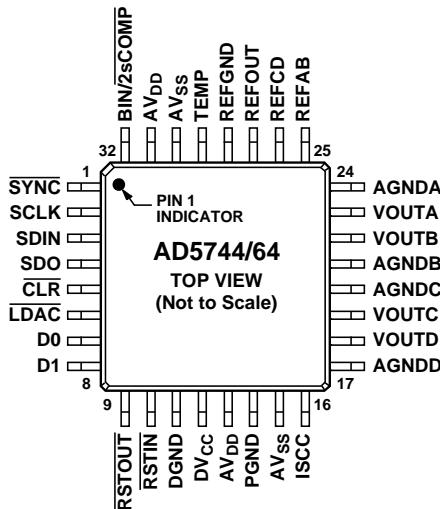


Figure 6. 32-Lead TQFP Pin Configuration Diagram

Table 5. Pin Function Descriptions

Pin No.	Mnemonic	Function
1	SYNC	Active <u>Low</u> Input. This is the frame synchronization signal for the serial interface. While SYNC is low, data is transferred in on the falling edge of SCLK.
2	SCLK ¹³	Serial Clock Input. Data is clocked into the shift register on the falling edge of SCLK. This operates at clock speeds up to 30 MHz.
3	SDIN ¹³	Serial Data Input. Data must be valid on the falling edge of SCLK.
4	SDO	Serial Data Output. Used to clock data from the serial register in daisy-chain or readback mode.
5	CLR ¹³	Active Low Input. Asserting this pin sets the DAC registers to 0x0000.
6	LDAC	Load DAC. Logic input. This is used to update the DAC registers and consequently the analog output. When tied permanently low, the addressed DAC register is updated on the 24 th clock of the serial register write. If LDAC is held high during the write cycle, the DAC input register is updated but the output is held off until the falling edge of LDAC. In this mode, all analog outputs can be updated simultaneously on the falling edge of LDAC.
7, 8	D0, D1	D0 and D1 form a digital I/O port. The user can configure these pins as inputs or outputs that are configurable and readable over the serial interface. When configured as inputs, these pins have weak internal pull-ups to DV _{CC} .
9	RSTOUT	Reset Logic Output. This is the output from the on-chip voltage monitor used in the reset circuit. If desired, it may be used to control other system components.
10	RSTIN	Reset Logic Input. This input allows external access to the internal reset logic. Applying a Logic 0 to this input resets the DAC output to 0 V. In normal operation, RSTIN should be tied to Logic 1.
11	DGND	Digital GND Pin.
12	DV _{CC}	Digital Supply Pin. Voltage ranges from 2.7 V to 5.5 V. When programmed as outputs, D0 and D1 are referenced to DV _{CC} .
13, 31	AV _{DD}	Positive Analog Supply Pins. Voltage ranges from 11.4 V to 16.5 V.
14	PGND	Ground Reference Point for Analog Circuitry.
15, 30	AV _{SS}	Negative Analog Supply Pins. Voltage ranges from -11.4 V to -16.5 V.

¹³ Internal pull-up device on this logic input. Therefore, it can be left floating and will default to a logic high condition.

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Pin No.	Mnemonic	Function
16	ISCC	This pin is used in association with an external resistor to AGND to program the short-circuit current of the output amplifiers.
17	AGNDD	Ground Reference Pin for DAC D Output amplifier.
18	VOUTD	Analog Output Voltage of DAC D. Buffered output with a nominal full-scale output range of ± 10 V. The output amplifier is capable of directly driving a $10\text{ k}\Omega$, 200 pF load.
19	VOUTC	Analog Output Voltage of DAC C. Buffered output with a nominal full-scale output range of ± 10 V. The output amplifier is capable of directly driving a $10\text{ k}\Omega$, 200 pF load.
20	AGNDC	Ground Reference Pin for DAC C Output Amplifier.
21	AGNDB	Ground Reference pin for DAC B Output Amplifier.
22	VOUTB	Analog Output Voltage of DAC B. Buffered output with a nominal full-scale output range of ± 10 V. The output amplifier is capable of directly driving a $10\text{ k}\Omega$, 200 pF load.
23	VOUTA	Analog Output Voltage of DAC A. Buffered output with a nominal full-scale output range of ± 10 V. The output amplifier is capable of directly driving a $10\text{ k}\Omega$, 200 pF load.
24	AGNDA	Ground Reference Pin for DAC A Output Amplifier.
25	REFAB	External Reference Voltage Input for Channels A and B. Reference input range is 1 V to 5 V; programs the full-scale output voltage. REFIN = 5 V for specified performance.
26	REFCD	External Reference Voltage Input for Channels C and D. Reference input range is 1 V to 5 V; programs the full-scale output voltage. REFIN = 5 V for specified performance.
27	REFOUT	Reference Output. This is the buffered reference output from the internal voltage reference. The internal reference is $5\text{ V} \pm 1\text{ mV}$, with a reference tempco of $10\text{ ppm}/^\circ\text{C}$.
28	REFGND	Reference Ground Return for the Reference Generator and Buffers.
29	TEMP	This pin provides an output voltage proportional to temperature. The output voltage is 1.5 V typical at 25°C ; variation with temperature is $5\text{ mV}/^\circ\text{C}$.
32	BIN/2sCOMP	Determines the DAC Coding. When set to a logic high, input coding is offset binary. When set to a logic low, input coding is two's complement. (See Table 6 and Table 7)

TERMINOLOGY

Relative Accuracy

For the DAC, relative accuracy or Integral Nonlinearity (INL) is a measure of the maximum deviation, in LSBs, from a straight line passing through the endpoints of the DAC transfer function. A typical INL vs. code plot can be seen in Figure ?.

Differential Nonlinearity

Differential Nonlinearity (DNL) is the difference between the measured change and the ideal 1 LSB change between any two adjacent codes. A specified differential nonlinearity of ± 1 LSB maximum ensures monotonicity. This DAC is guaranteed monotonic by design. A typical DNL vs. code plot can be seen in Figures ?.

Monotonicity

A DAC is monotonic, if the output either increases or remains constant for increasing digital input code. The AD5744/64 is monotonic over its full operating temperature range

Bipolar Zero Error

Bipolar zero error is the deviation of the analog output from the ideal half-scale output of 0 V when the DAC register is loaded with 0x8000 (Offset Binary coding) or 0x0000 (2sComplement coding)

Full-Scale Error

Full-scale error is a measure of the output error when full-scale code is loaded to the DAC register. Ideally the output voltage should be full scale value – 1 LSB. Full-scale error is expressed in percentage of full-scale range. A plot of full-scale error vs. temperature can be seen in Figure ?.

Negative Full-Scale Error / Zero Scale Error

Negative full-scale error is the error in the DAC output voltage when 0x0000 (Offset Binary coding) or 0x8000 (2sComplement coding) is loaded to the DAC register. Ideally the output voltage should be negative full scale value – 1 LSB.

Output Voltage Settling Time

Output voltage settling time is the amount of time it takes for the output to settle to a specified level for a full-scale input change.

Slew Rate

The slew rate of a device is a limitation in the rate of change of the output voltage. The output slewing speed of a voltage-output D/A converter is usually limited by the slew rate of the amplifier used at its output. Slew rate is measured from 10% to

90% of the output signal and is given in V/ μ s.

Gain Error

This is a measure of the span error of the DAC. It is the deviation in slope of the DAC transfer characteristic from the ideal, expressed as a percentage of the full-scale range.

Total Unadjusted Error

Total Unadjusted Error (TUE) is a measure of the output error taking all the various errors into account. A typical TUE vs. code plot can be seen in Figure ?.

Zero-Code Error Drift

This is a measure of the change in zero-code error with a change in temperature. It is expressed in μ V/ $^{\circ}$ C.

Gain Error Drift

This is a measure of the change in gain error with changes in temperature. It is expressed in (ppm of full-scale range)/ $^{\circ}$ C.

Digital-to-Analog Glitch Impulse

Digital-to-analog glitch impulse is the impulse injected into the analog output when the input code in the DAC register changes state. It is normally specified as the area of the glitch in nV secs and is measured when the digital input code is changed by 1 LSB at the major carry transition (7FFF Hex to 8000 Hex). See Figure ?.

Digital Feedthrough

Digital feedthrough is a measure of the impulse injected into the analog output of the DAC from the digital inputs of the DAC but is measured when the DAC output is not updated. It is specified in nV secs and measured with a full-scale code change on the data bus, i.e., from all 0s to all 1s and vice versa.

Power Supply Sensitivity

Power supply sensitivity indicates how the output of the DAC is affected by changes in the power supply voltage.

DC Crosstalk

This is the dc change in the output level of one DAC in response to a change in the output of another DAC. It is measured with a full-scale output change on one DAC while monitoring another DAC. It is expressed in μ V.

DAC-to-DAC Crosstalk

This is the glitch impulse transferred to the output of one DAC due to a digital code change and subsequent output change of

another DAC. This includes both digital and analog crosstalk. It is measured by loading one of the DACs with a full-scale code change (all 0s to all 1s and vice versa) with LDAC low and monitoring the output of another DAC. The energy of the glitch is expressed in nV-s.

Channel-to-Channel Isolation

This is the ratio of the amplitude of the signal at the output of one DAC to a sine wave on the reference input of another DAC. It is measured in dB.

TYPICAL PERFORMANCE CHARACTERISTICS

GENERAL DESCRIPTION

The AD5744/64 is a quad 14/16-bit, serial input, bipolar voltage output DAC. It operates from supply voltages of ± 11.4 V to ± 16.5 V and has a buffered output voltage of up to ± 10.5 V. Data is written to the AD5744/64 in a 24-bit word format, via a 3-wire serial interface. The device also offers an SDO pin, which is available for daisy chaining or readback.

The AD5744/64 incorporates a power-on reset circuit, which ensures that the DAC registers power up loaded with 0x0000. The AD5744/64 also features a digital I/O port that may be programmed via the serial interface, an analog temperature sensor, on-chip 10 ppm/ $^{\circ}$ C voltage reference, on-chip reference buffers and per channel digital gain and offset registers.

DAC ARCHITECTURE

The DAC architecture of the AD5744/64 consists of a 14/16-bit current-mode segmented R-2R DAC. The simplified circuit diagram for the DAC section is shown in Figure 13.

The four MSBs of the 14/16-bit data word are decoded to drive 15 switches, E1 to E15. Each of these switches connects one of the 15 matched resistors to either AGND or IOUT. The remaining 12 bits of the data word drive switches S0 to S11 of the 12-bit R-2R ladder network.

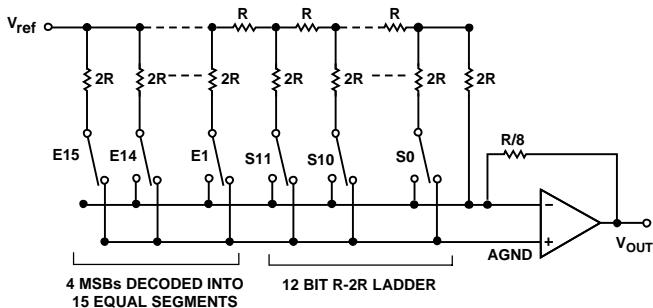


Figure 7. DAC Ladder Structure

REFERENCE BUFFERS

The AD5744/64 can operate with either an external or internal reference. The reference inputs (REFAB and REFCD) have an input range up to 5 V. This input voltage is then used to provide a buffered positive and negative reference for the DAC cores. The positive reference is given by

$$+V_{REF} = 2^* V_{REF}$$

While the negative reference to the DAC cores is given by

$$-V_{REF} = -2^* V_{REF}$$

These positive and negative reference voltages (along with the gain register values) define the output ranges of the DACs.

SERIAL INTERFACE

The AD5744/64 is controlled over a versatile 3-wire serial interface that operates at clock rates of up to 30 MHz and is compatible with SPI, QSPI, MICROWIRE and DSP standards.

Input Shift Register

The input shift register is 24 bits wide. Data is loaded into the device MSB first as a 24-bit word under the control of a serial clock input, SCLK. The input register consists of a read/write bit, three register select bits, three DAC address bits and 14/16 data bits as shown in Table 8. The timing diagram for this operation is shown in Figure 2.

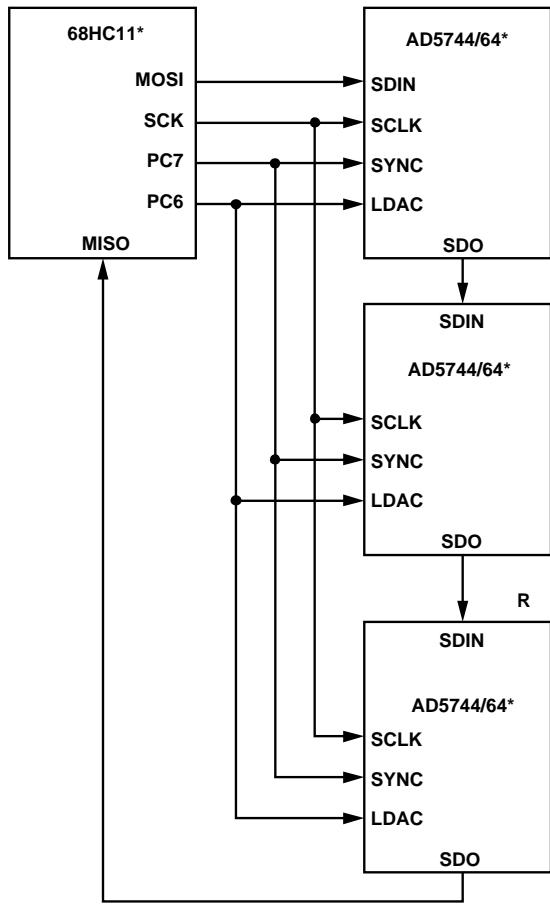
Upon power-up the DAC registers are loaded with zero code (0x0000). The corresponding output voltage depends on the state of the BIN/2sCOMP pin. If the BIN/2sCOMP pin is tied to DGND then the data coding is 2sComplement and the outputs will power-up to 0V. If the BIN/2sCOMP pin is tied high then the data coding is Offset binary and the outputs will power-up to Negative Full-scale.

Standalone Operation

The serial interface works with both a continuous and noncontinuous serial clock. A continuous SCLK source can only be used if SYNC is held low for the correct number of clock cycles. In gated clock mode, a burst clock containing the exact number of clock cycles must be used and SYNC must be taken high after the final clock to latch the data. The first falling edge of SYNC starts the write cycle. Exactly 24 falling clock edges must be applied to SCLK before SYNC is brought back high again; if SYNC is brought high before the 24th falling SCLK edge, the write is aborted. If more than 24 falling SCLK edges are applied before SYNC is brought high, the input data will be corrupted. The input register addressed is updated on the rising edge of SYNC. In order for another serial transfer to take place, SYNC must be brought low again. After the end of the serial data transfer, data is automatically transferred from the input shift register to the input register of the addressed DAC.

When the data has been transferred into the input register of the addressed DAC, all DAC registers and outputs can be updated by taking LDAC low while SYNC is high.

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*ADDITIONAL PINS OMITTED FOR CLARITY

Figure 8. Daisy chaining the AD5744/64

Daisy-Chain Operation

For systems that contain several devices, the SDO pin may be used to daisy-chain several devices together. This daisy-chain mode can be useful in system diagnostics and in reducing the number of serial interface lines. The first falling edge of SYNC starts the write cycle. The SCLK is continuously applied to the input shift register when SYNC is low. If more than 24 clock pulses are applied, the data ripples out of the shift register and appears on the SDO line. This data is clocked out on the rising edge of SCLK and is valid on the falling edge. By connecting the SDO of the first device to the DIN input of the next device in the chain, a multidevice interface is constructed. Each device in the system requires 24 clock pulses. Therefore, the total number of clock cycles must equal $24N$, where N is the total number of AD5744/64s in the chain. When the serial transfer to all devices is complete, SYNC is taken high. This latches the input data in each device in the daisy chain and prevents any further data from being clocked into the input shift register. The serial clock may be a continuous or a gated clock. A continuous SCLK source can only be used if SYNC is held low for the correct number of clock cycles. In gated clock mode, a burst clock

containing the exact number of clock cycles must be used and SYNC must be taken high after the final clock to latch the data.

Readback Operation

Readback mode is invoked by setting the R/W bit = 1 in the serial input register write. With R/W = 1, Bits A2–A0, in association with Bits REG2, REG1, and REG0, select the register to be read. The remaining data bits in the write sequence are don't cares. During the next SPI write, the data appearing on the SDO output will contain the data from the previously addressed register. For a read of a single register, the NOP command can be used in clocking out the data from the selected register on SDO. The readback diagram in Figure 4 shows the readback sequence. For example, to read back the fine gain register of Channel A on the AD5744/64, the following sequence should be implemented. First, write 0xA0XXXX to the AD5744/64 input register. This configures the AD5744/64 for read mode with the fine gain register of Channel A selected. Note that all the data bits, DB15 to DB0, are don't cares. Follow this with a second write, a NOP condition, 0x00XXXX. During this write, the data from the fine gain register is clocked out on the SDO line, i.e., data clocked out will contain the data from the fine gain register in Bits DB5 to DB0.

SIMULTANEOUS UPDATING VIA LDAC

After data has been transferred into the input register of the DACs, there are two ways in which the DAC registers and DAC outputs can be updated. Depending on the status of both SYNC and LDAC.

Individual DAC Updating

In this mode, LDAC is held low while data is being clocked into the input shift register. The addressed DAC output is updated on the rising edge of SYNC.

Simultaneous Updating of All DACs

In this mode, LDAC is held high while data is being clocked into the input shift register. All DAC outputs are updated by taking LDAC low any time after SYNC has been taken high. The update now occurs on the falling edge of LDAC.

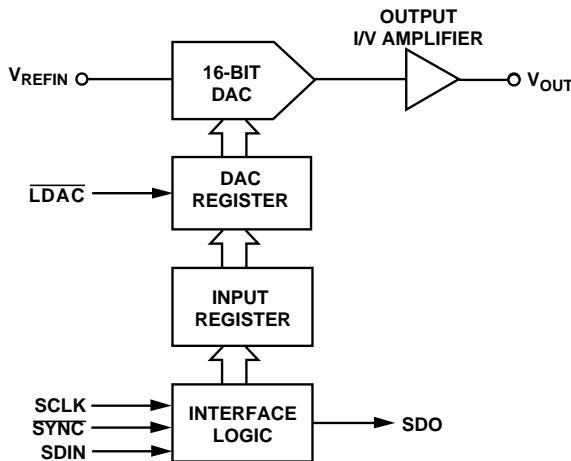


Figure 9. Simplified Serial Interface showing input loading circuitry for one DAC Channel

TRANSFER FUNCTION

Table 6 and Table 7 Show the ideal input code to output voltage relationship for the AD5744/64 for both Offset binary and twos complement data coding.

Table 6. Ideal output voltage to input code relationship for the AD5764

Digital Input				Analog Output
Offset Binary Data Coding				
MSB	LSB			V _{OUT}
1111	1111	1111	1111	+2 V _{REF} x (32767/32768)
1000	0000	0000	0001	+2 V _{REF} x (1/32768)
1000	0000	0000	0000	0 V
0111	1111	1111	1111	-2 V _{REF} x (1/32768)
0000	0000	0000	0000	-2 V _{REF} x (32767/32768)

Twos Complement Data Coding				
MSB	LSB			V _{OUT}
0111	1111	1111	1111	+2 V _{REF} x (32767/32768)
0000	0000	0000	0001	+2 V _{REF} x (1/32768)
0000	0000	0000	0000	0 V
1111	1111	1111	1111	-2 V _{REF} x (1/32768)
1000	0000	0000	0000	-2 V _{REF} x (32767/32768)

Table 7. Ideal output voltage to input Code relationship for the AD5744

Digital Input				Analog Output
Offset Binary Data Coding				
MSB	LSB			V _{OUT}
11	1111	1111	1111	+2 V _{REF} x (8192/8192)
10	0000	0000	0001	+2 V _{REF} x (1/8192)
10	0000	0000	0000	0 V
01	1111	1111	1111	-2 V _{REF} x (1/8192)
00	0000	0000	0000	-2 V _{REF} x (8192/8192)

Digital Input				
Twos Complement Data Coding				
MSB	LSB			V _{OUT}
01	1111	1111	1111	+2 V _{REF} x (8192/8192)
00	0000	0000	0001	+2 V _{REF} x (1/8192)
00	0000	0000	0000	0 V
11	1111	1111	1111	-2 V _{REF} x (1/8192)
10	0000	0000	0000	-2 V _{REF} x (8192/8192)

The output voltage expression for the AD5764 is given by:

$$V_{OUT} = -2 \times V_{REFIN} + 4 \times V_{REFIN} \left[\frac{D}{65536} \right]$$

The output voltage expression for the AD5744 is given by:

$$V_{OUT} = -2 \times V_{REFIN} + 4 \times V_{REFIN} \left[\frac{D}{16384} \right]$$

where:

D is the decimal equivalent of the code loaded to the DAC.

V_{REFIN} is the reference voltage applied at the REFIN pin.

ASYNCHRONOUS CLEAR (CLR)

CLR is an active low, level sensitive clear that allows the outputs to be cleared to either 0 V (Offset binary coding) or negative full scale (twos complement coding). It is necessary to maintain CLR low for a minimum amount of time (refer to Figure 3) for the operation to complete. When the CLR signal is returned high, the output remains at the cleared value until a new value is programmed. The CLR signal has priority over LDAC and SYNC. A clear can also be initiated through software by writing the command 0x04XXXX to the AD5744/64.

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Table 8. AD5744/64 Input Register Format

MSB	DB22	DB21	DB20	DB19	DB18	DB17	DB16	DB15	DB14	DB13	DB12	DB11	DB10	DB9	DB8	DB7	DB6	DB5	DB4	DB3	DB2	DB1	LSB
R/W	0	REG2	REG1	REG0	A2	A1	A0	DATA															

Table 9. Input Register Bit Functions

R/W	Indicates a read from or a write to the addressed register.																										
REG2, REG1, REG0	Used in association with the address bits to determine if a read or write operation is to the data register, offset register, gain register, or function register.																										
	<table> <thead> <tr> <th>REG2</th> <th>REG1</th> <th>REG0</th> <th>Function</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>0</td> <td>0</td> <td>Function Register</td> </tr> <tr> <td>0</td> <td>1</td> <td>0</td> <td>Data Register</td> </tr> <tr> <td>0</td> <td>1</td> <td>1</td> <td>Coarse Gain Register</td> </tr> <tr> <td>1</td> <td>0</td> <td>0</td> <td>Fine Gain Register</td> </tr> <tr> <td>1</td> <td>0</td> <td>1</td> <td>Offset Register</td> </tr> </tbody> </table>			REG2	REG1	REG0	Function	0	0	0	Function Register	0	1	0	Data Register	0	1	1	Coarse Gain Register	1	0	0	Fine Gain Register	1	0	1	Offset Register
REG2	REG1	REG0	Function																								
0	0	0	Function Register																								
0	1	0	Data Register																								
0	1	1	Coarse Gain Register																								
1	0	0	Fine Gain Register																								
1	0	1	Offset Register																								
A2, A1, A0	These bits are used to decode the DAC channels																										
	<table> <thead> <tr> <th>A2</th> <th>A1</th> <th>A0</th> <th>Channel Address</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>0</td> <td>0</td> <td>DAC A</td> </tr> <tr> <td>0</td> <td>0</td> <td>1</td> <td>DAC B</td> </tr> <tr> <td>0</td> <td>1</td> <td>0</td> <td>DAC C</td> </tr> <tr> <td>0</td> <td>1</td> <td>1</td> <td>DAC D</td> </tr> <tr> <td>1</td> <td>0</td> <td>0</td> <td>ALL DACs</td> </tr> </tbody> </table>			A2	A1	A0	Channel Address	0	0	0	DAC A	0	0	1	DAC B	0	1	0	DAC C	0	1	1	DAC D	1	0	0	ALL DACs
A2	A1	A0	Channel Address																								
0	0	0	DAC A																								
0	0	1	DAC B																								
0	1	0	DAC C																								
0	1	1	DAC D																								
1	0	0	ALL DACs																								
D15 – D0	Data Bits																										

FUNCTION REGISTER

The Function Register is addressed by setting the three REG bits to 000. The values written to the address bits and the data bits determine the function addressed. The Functions available through the function register are shown in Table 10 and

Table 11.

Table 10. Function Register Options

REG2	REG1	REG0	A2	A1	A0	DB15 .. DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	NOP, Data = Don't Care						
0	0	0	0	0	1	Don't Care	Local-Ground-Offset Adjust	D1 Direction	D1 Value	D0 Direction	D0 Value	SDO Disable
0	0	0	1	0	0	CLR, Data = Don't Care						
0	0	0	1	0	1	LOAD, Data = Don't Care						

Table 11. Explanation of Function Register Options

NOP	No operation instruction used in readback operations.
Local-Ground-Offset Adjust	Set by the user to enable local-ground-offset adjust function. Cleared by the user to disable local-ground-offset adjust function (default).
D0 / D1 Direction	Set by the user to enable D0/D1 as outputs. Cleared by the user to enable D0/D1 as inputs (default). Have weak internal pull-ups.
D0 / D1 Value	I/O port status bits. Logic values written to these locations determine the logic outputs on the D0 and D1 pins when configured as outputs. These bits indicate the status of the D0 and D1 pins when the I/O port is active as an input. When enabled as inputs, these bits are don't cares during a write operation.
SDO Disable	Set by the user to disable the SDO output. Cleared by the user to enable the SDO output (default).
CLR	Addressing this function resets the DAC outputs to 0 V in two's complement mode and negative full scale in binary mode.
LOAD	Addressing this function updates the DAC registers and consequently the analog outputs.

DATA REGISTER

The Data register is addressed by setting the three REG bits to 010. The DAC address bits select with which DAC Channel the Data transfer is to take place (Refer to Table 9). The data bits are in positions D15 to D0 for the AD5764 as shown in Table 12 and D13 to D0 for the AD5744 as shown in Table 13.

Table 12. Programming the AD5764 Data Register

REG2	REG1	REG0	A2	A1	A0	DB15	DB14	DB13	DB12	DB11	DB10	DB9	DB8	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	1	0	DAC Address			16 Bit DAC Data															

Table 13. Programming the AD5744 Data Register

REG2	REG1	REG0	A2	A1	A0	DB15	DB14	DB13	DB12	DB11	DB10	DB9	DB8	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	1	0	DAC Address			14 Bit DAC Data															

COARSE GAIN REGISTER

The Coarse Gain Register is addressed by setting the three REG bits to 011. The DAC address bits select with which DAC Channel the Data transfer is to take place (Refer to Table 9). The Coarse Gain Register is a 2-bit register and allows the user to select the output range of each DAC as shown in Table 15.

Table 14. Programming the Coarse Gain Register

REG2	REG1	REG0	A2	A1	A0	DB15 DB2	DB1	DB0
0	1	1	DAC Address			Don't Care	CG1	CG0

Table 15. Output Range Selection

Output Range	CG1	CG0
$\pm 10\text{ V}$	0	0
$\pm 10.25\text{ V}$	0	1
$\pm 10.5\text{ V}$	1	0

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FINE GAIN REGISTER

The Fine Gain Register is addressed by setting the three REG bits to 100. The DAC address bits select with which DAC Channel the Data transfer is to take place (Refer to Table 9). The Fine Gain Register is a 6-bit register and allows the user to adjust the gain of each DAC channel by -32 LSBs to +31 LSBs in 1 LSB steps as shown in

Table 16 and

Table 17.

Table 16. Programming AD5764 Fine Gain Register

REG2	REG1	REG0	A2	A1	A0	DB15 DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	0	0	DAC Address			Don't Care	FG5	FG4	FG3	FG2	FG1	FG0

Table 17. Fine Gain Register Options

Gain Adjustment	FG5	FG4	FG3	FG2	FG1	FG0
+31 LSBs	0	1	1	1	1	1
+30 LSBs	0	1	1	1	1	0
-	-	-	-	-	-	-
No Adjustment	0	0	0	0	0	0
-	-	-	-	-	-	-
-31 LSBs	1	0	0	0	0	1
-32 LSBs	1	0	0	0	0	0

OFFSET REGISTER

The Offset Register is addressed by setting the three REG bits to 101. The DAC address bits select with which DAC Channel the Data transfer is to take place (Refer to Table 9). The Offset Register is an 8-bit register and allows the user to adjust the offset of each channel by - 15.875 LSBs to + 16 LSBs in steps of 1/8 LSB as shown in Table 18 and Table 19.

Table 18. Programming the Offset Register

REG2	REG1	REG0	A2	A1	A0	DB15 DB8	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	0	1	DAC Address			Don't Care	OF7	OF6	OF5	OF4	OF3	OF2	OF1	OF0

Table 19. Offset Register options

Offset Adjustment	OF7	OF6	OF5	OF4	OF3	OF2	OF1	OF0
+15.875 LSBs	0	1	1	1	1	1	1	1
+16.5 LSBs	0	1	1	1	1	1	1	0
-	-	-	-	-	-	-	-	-
No Adjustment	0	0	0	0	0	0	0	0
-	-	-	-	-	-	-	-	-
-15.875 LSBs	1	0	0	0	0	0	0	1
-16 LSBs	1	0	0	0	0	0	0	0

AD5744/64 FEATURES

ANALOG OUTPUT CONTROL

In many industrial process control applications, it is vital that the output voltage be controlled during power up and during brownout conditions. When the supply voltages are changing, the VOUT pin is clamped to 0 V via a low impedance path. To prevent the output amp being shorted to 0 V during this time, transmission gate G1 is also opened. These conditions are maintained until the power supplies stabilize and a valid word is written to the DAC register. At this time, G2 opens and G1 closes. Both transmission gates are also externally controllable via the Reset In (RSTIN) control input. For instance, if RSTIN is driven from a battery supervisor chip, the RSTIN input is driven low to open G1 and close G2 on power-off or during a brownout. Conversely, the on-chip voltage detector output (RSTOUT) is also available to the user to control other parts of the system. The basic transmission gate functionality is shown in Figure 10.

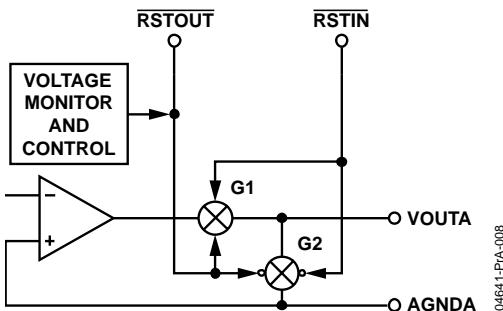


Figure 10. Analog Output Control Circuitry

DIGITAL OFFSET AND GAIN CONTROL

The AD5744/64 incorporates a digital offset adjust function with a ± 16 LSB adjust range and 0.125 LSB resolution. The gain register allows the user to adjust the AD5744/64's full-scale output range. The full-scale output can be programmed to achieve full-scale ranges of ± 10 V, ± 10.25 V, and ± 10.5 V. A fine gain trim is also available, allowing a trim range of ± 16 LSB in 1 LSB steps.

PROGRAMMABLE SHORT-CIRCUIT PROTECTION

The short-circuit current of the output amplifiers can be programmed by inserting an external resistor between the ISCC pin and AGND. The programmable range for the current is 500 μ A to 10 mA, corresponding to a resistor range of 120 k Ω to 6 k Ω .

The resistor value is calculated as follows;

$$R = \frac{60}{I_{sc}}$$

If the ISCC pin is left unconnected the short circuit current limit defaults to 5 mA. It should be noted that limiting the short circuit current to a small value can affect the slew rate of the output when driving into a capacitive load, therefore the value of short-circuit current programmed should take into account the size of the capacitive load being driven.

DIGITAL I/O PORT

The AD5744/64 contains a 2-bit digital I/O port (D1 and D0); these bits can be configured as inputs or outputs independently, and can be driven or have their values read back via the serial interface. The I/O port signals are referenced to DV_{CC} and DGND. When configured as outputs, they can be used as control signals to multiplexers or can be used to control calibration circuitry elsewhere in the system. When configured as inputs, the logic signals from limit switches, for example can be applied to D0 and D1 and can be read back via the digital interface.

TEMPERATURE SENSOR

The on-chip temperature sensor provides a voltage output that is linearly proportional to the Centigrade temperature scale. The typical accuracy of the temperature sensor is $\pm 1^\circ\text{C}$ at $+25^\circ\text{C}$ and $\pm 5^\circ\text{C}$ over the -40°C to $+105^\circ\text{C}$ range. Its nominal output voltage is 1.5V at $+25^\circ\text{C}$, varying at 5 mV/ $^\circ\text{C}$, giving a typical output range of 1.175V to 1.9 V over the full temperature range. Its low output impedance, low self heating, and linear output simplify interfacing to temperature control circuitry and A/D converters.

LOCAL GROUND OFFSET ADJUST

The AD5744/64 incorporates a Local Ground Offset Adjust feature which when enabled in the Function Register adjusts the DAC outputs for voltage differences between the individual DAC ground pins and the REFGND pin ensuring that the DAC output voltages are always with respect to the local DAC ground pin. For instance if pin AGNDA is at +5mV with respect to the REFGND pin and VOUTA is measured with respect to AGNDA then a +5mV error will result, enabling the Local Ground Offset Adjust feature will offset VOUTA by +5mV eliminating the error.

APPLICATIONS INFORMATION

TYPICAL OPERATING CIRCUIT

Figure 11 shows the typical operating circuit for the AD5744/64. The only external components needed for this precision 14/16-bit DAC are decoupling capacitors on the supply pins, R-C connection from REfout to REFAB and REFCD and a short circuit current setting resistor. Because the device incorporates a voltage reference, and reference buffers, it eliminates the need for an external bipolar reference and associated buffers. This leads to an overall saving in both cost and board space.

In the circuit below, VDD and VSS are both connected to ± 15 V, but VDD and VSS can operate with supplies from ± 11.4 V to ± 16.5 V. In Figure 11, AGNDA is connected to REFGND, but the option of Force/Sense is included on this device, if required by the user.

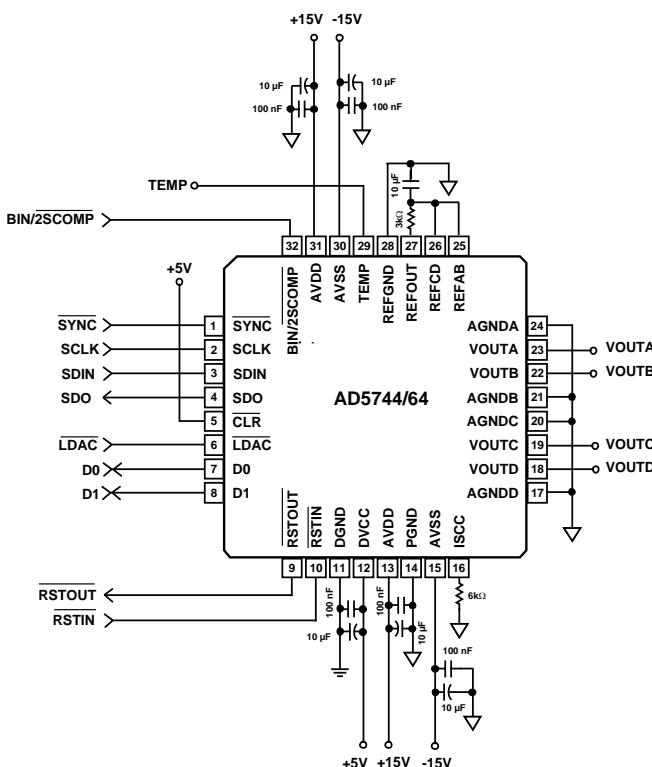


Figure 11. Typical operating circuit

Precision Voltage Reference Selection

To achieve the optimum performance from the AD5744/64 over its full operating temperature range an external voltage reference must be used. Thought should be given to the selection of a precision voltage reference. The AD5744/64 has two reference inputs, REFAB and REFCD. The voltages applied to the reference inputs are used to provide a buffered positive and negative reference for the DAC cores. Therefore, any error

in the voltage reference is reflected in the outputs of the device.

There are four possible sources of error to consider when choosing a voltage reference for high accuracy applications: initial accuracy, temperature coefficient of the output voltage, long term drift and output voltage noise.

Initial accuracy error on the output voltage of an external reference could lead to a full-scale error in the DAC. Therefore, to minimize these errors, a reference with low initial accuracy error specification is preferred. Also, choosing a reference with an output trim adjustment, such as the ADR425, allows a system designer to trim system errors out by setting the reference voltage to a voltage other than the nominal. The trim adjustment can also be used at temperature to trim out any error.

Long term drift is a measure of how much the reference output voltage drifts over time. A reference with a tight long-term drift specification ensures that the overall solution remains relatively stable over its entire lifetime.

The temperature coefficient of a reference's output voltage affects INL, DNL and TUE. A reference with a tight temperature coefficient specification should be chosen to reduce the dependence of the DAC output voltage on ambient conditions.

In high accuracy applications, which have a relatively low noise budget, reference output voltage noise needs to be considered. Choosing a reference with as low an output noise voltage as practical for the system resolution required is important. Precision voltage references such as the ADR435 (XFET design) produce low output noise in the 0.1 Hz to 10 Hz region. However, as the circuit bandwidth increases, filtering the output of the reference may be required to minimize the output noise.

Table 20. Partial List of Precision References Recommended for use with the AD5744/64

Part No.	Initial Accuracy (mV max)	Long-Term Drift (ppm typ)	Temp Drift (ppm/°C max)	0.1 Hz to 10 Hz Noise (µV p-p typ)
ADR435	± 6	30	3	3.4
ADR425	± 6	50	3	3.4
ADR02	± 5	50	3	15
ADR395	± 6	50	25	5
AD586	± 2.5	15	10	4

LAYOUT GUIDELINES

In any circuit where accuracy is important, careful consideration of the power supply and ground return layout helps to ensure the rated performance. The printed circuit board on which the AD5744/64 is mounted should be designed so that the analog and digital sections are separated and confined to certain areas of the board. If the AD5744/64 is in a system where multiple devices require an AGND-to-DGND connection, the connection should be made at one point only. The star ground point should be established as close as possible to the device.

The AD5744/64 should have ample supply bypassing of $10\ \mu\text{F}$ in parallel with $0.1\ \mu\text{F}$ on each supply located as close to the package as possible, ideally right up against the device. The $10\ \mu\text{F}$ capacitors are the tantalum bead type. The $0.1\ \mu\text{F}$ capacitor should have low effective series resistance (ESR) and low effective series inductance (ESI) such as the common ceramic types, which provide a low impedance path to ground at high frequencies to handle transient currents due to internal logic switching.

The power supply lines of the AD5744/64 should use as large a trace as possible to provide low impedance paths and reduce the effects of glitches on the power supply line. Fast switching signals such as clocks should be shielded with digital ground to avoid radiating noise to other parts of the board, and should never be run near the reference inputs. A ground line routed between the SDIN and SCLK lines helps reduce crosstalk between them (not required on a multilayer board, which has a separate ground plane, but separating the lines helps). It is essential to minimize noise on the reference inputs, because it couples through to the DAC output.

Avoid crossover of digital and analog signals. Traces on opposite sides of the board should run at right angles to each other. This reduces the effects of feed through the board. A microstrip technique is by far the best, but not always possible with a double-sided board. In this technique, the component side of the board is dedicated to ground plane, while signal traces are placed on the solder side.

ISOLATED INTERFACE

In many process control applications, it is necessary to provide an isolation barrier between the controller and the unit being controlled. Opto-isolators can provide voltage isolation in excess of 3 kV. The serial loading structure of the AD5744/64 makes it ideal for opto-isolated interfaces, because the number of interface lines is kept to a minimum. Figure 12 shows a 4-channel isolated interface to the AD5744/64. To reduce the number of opto-isolators, if the simultaneous updating of the

DAC is not required, the LDAC pin may be tied permanently low. The DAC can then be updated on the rising edge of SYNC.

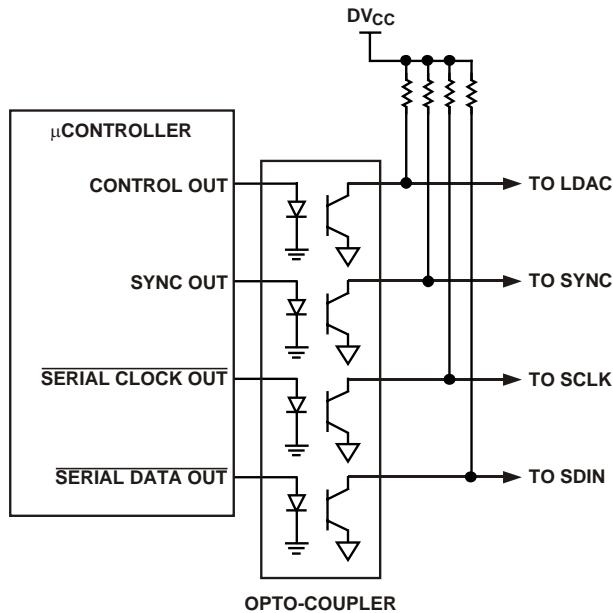


Figure 12. Isolated Interface

MICROPROCESSOR INTERFACING

Microprocessor interfacing to the AD5744/64 is via a serial bus that uses standard protocol compatible with microcontrollers and DSP processors. The communications channel is a 3-wire (minimum) interface consisting of a clock signal, a data signal, and a synchronization signal. The AD5744/64 requires a 24-bit data word with data valid on the falling edge of SCLK.

For all the interfaces, the DAC output update may be done automatically when all the data is clocked in, or it may be done under the control of LDAC. The contents of the DAC register may be read using the readback function.

AD5744/64 to MC68HC11 Interface

Figure 13 shows an example of a serial interface between the AD5744/64 and the MC68HC11 microcontroller. The serial peripheral interface (SPI) on the MC68HC11 is configured for master mode (MSTR = 1), clock polarity bit (CPOL = 0), and the clock phase bit (CPHA = 1). The SPI is configured by writing to the SPI control register (SPCR)—see the *68HC11 User Manual*. SCK of the 68HC11 drives the SCLK of the AD5744/64, the MOSI output drives the serial data line (DIN) of the AD5744/64, and the MISO input is driven from SDO. The SYNC is driven from one of the port lines, in this case PC7.

When data is being transmitted to the AD5744/64, the SYNC line

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(PC7) is taken low and data is transmitted MSB first. Data appearing on the MOSI output is valid on the falling edge of SCK. Eight falling clock edges occur in the transmit cycle, so, in order to load the required 24-bit word, PC7 is not brought high until the third 8-bit word has been transferred to the DAC's input shift register.

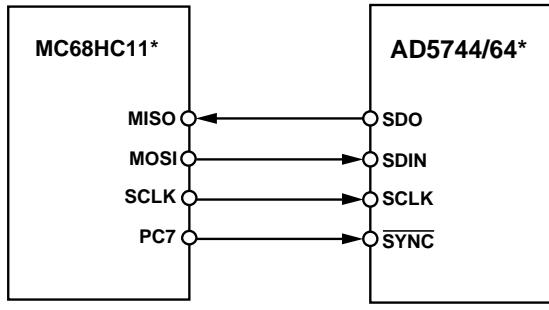


Figure 13. AD5744/64 to MC68HC11 Interface

LDAC is controlled by the PC6 port output. The DAC can be updated after each 3-byte transfer by bringing LDAC low. This example does not show other serial lines for the DAC. If CLR were used, it could be controlled by port output PC5, for example.

AD5744/64 to 8051 Interface

The AD5744/64 requires a clock synchronized to the serial data. For this reason, the 8051 must be operated in Mode 0. In this mode, serial data enters and exits through RxD, and a shift clock is output on TxD.

P3.3 and P3.4 are bit programmable pins on the serial port and are used to drive SYNC and LDAC, respectively.

The 8051 provides the LSB of its SBUF register as the first bit in the data stream. The user must ensure that the data in the SBUF register is arranged correctly, because the DAC expects MSB first. When data is to be transmitted to the DAC, P3.3 is taken low. Data on RxD is clocked out of the microcontroller on the rising edge of TxD and is valid on the falling edge. As a result, no glue logic is required between this DAC and the microcontroller interface.

The 8051 transmits data in 8-bit bytes with only eight falling clock edges occurring in the transmit cycle. Because the DAC expects a 24-bit word, SYNC (P3.3) must be left low after the first eight bits are transferred. After the third byte has been transferred, the P3.3 line is taken high. The DAC may be updated using LDAC via P3.4 of the 8051.

AD5744/64 to ADSP2101/ADSP2103 Interface

An interface between the AD5744/64 and the ADSP2101/ADSP2103 is shown in Figure 14. The ADSP2101/ADSP2103 should be set up to operate in the SPORT transmit alternate framing mode. The ADSP2101/ADSP2103 are programmed

through the SPORT control register and should be configured as follows: internal clock operation, active low framing, and 24-bit word length.

Transmission is initiated by writing a word to the Tx register after the SPORT has been enabled. As the data is clocked out of the DSP on the rising edge of SCLK, no glue logic is required to interface the DSP to the DAC. In the interface shown, the DAC output is updated using the LDAC pin via the DSP.

Alternatively, the LDAC input could be tied permanently low, and then the update takes place automatically when TFS is taken high.

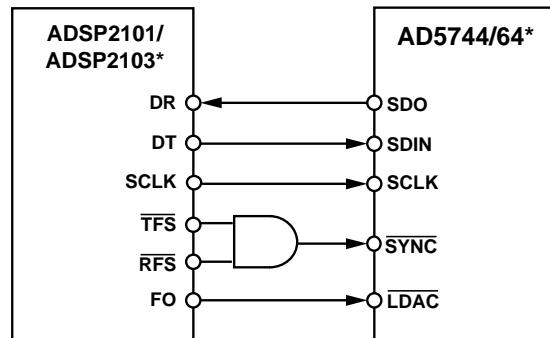


Figure 14. AD5744/64 to ADSP2101/ADSP2103 Interface

AD5744/64 to PIC16C6x/7x Interface

The PIC16C6x/7x synchronous serial port (SSP) is configured as an SPI master with the clock polarity bit set to 0. This is done by writing to the synchronous serial port control register (SSPCON). See the *PIC16/17 Microcontroller User Manual*. In this example, I/O port RA1 is being used to pulse SYNC and enable the serial port of the AD5744/64. This microcontroller transfers only eight bits of data during each serial transfer operation; therefore, three consecutive write operations are needed. Figure 15 shows the connection diagram.

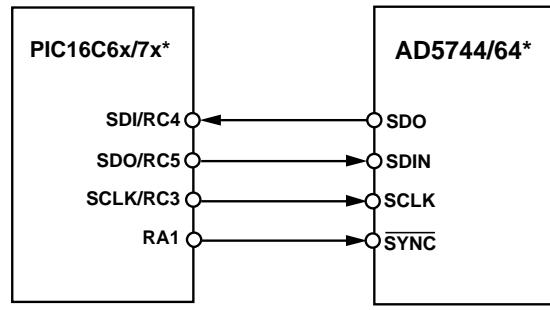


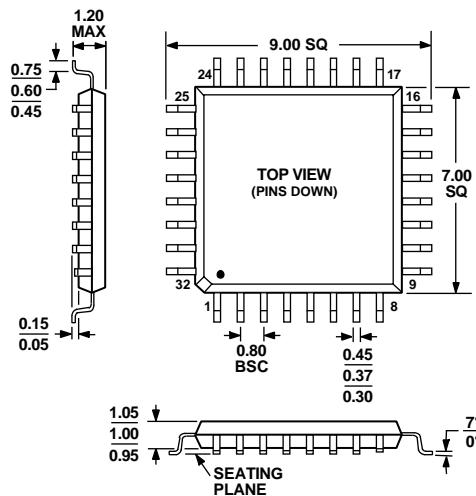
Figure 15. AD5744/64 to PIC16C6x/7x Interface

EVALUATION BOARD

The AD5744/64 comes with a full evaluation board to aid designers in evaluating the high performance of the part with a minimum of effort. All that is required with the evaluation board is a power supply, and a PC. The AD5744/64 evaluation kit includes a populated, tested AD5744/64 printed circuit board. The evaluation board interfaces to the USB interface of the PC. Software is available with the evaluation board, which allows the user to easily program the AD5744/64. The software runs on any PC that has Microsoft Windows® 98/2000/NT/XP installed.

An application note is available that gives full details on operating the evaluation board.

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MS-026ABA

Figure 16. 32-Lead Thin Quad Flatpack [TQFP]
(SU-32)

Dimensions shown in millimeters

ORDERING GUIDE

Model	Function	INL	Package Description	Package Option
AD5764CSU	Quad 16-Bit DAC	± 1 LSB Max	32-Lead TQFP	SU-32
AD5764BSU	Quad 16-Bit DAC	± 2 LSB Max	32-Lead TQFP	SU-32
AD5764ASU	Quad 16-Bit DAC	± 4 LSB Max	32-Lead TQFP	SU-32
AD5744CSU	Quad 14-Bit DAC	± 1 LSB Max	32-Lead TQFP	SU-32
AD5744BSU	Quad 14-Bit DAC	± 2 LSB Max	32-Lead TQFP	SU-32
AD5744ASU	Quad 14-Bit DAC	± 4 LSB Max	32-Lead TQFP	SU-32